Materials Declaration

Package	PBGA
Body Size	27 X 27
Ball Count	625
Option	PbFree
Ball Size	0.6

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	77	5.40 E-01	221855
Epoxy resin	10	7.01 E-02	28812
Phenol resin	10	7.01 E-02	28812
Metal Hydroxide	2.5	1.75 E-02	7203
Carbon Black	0.5	3.51 E-03	1441

Laminate

Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	25	2.84 E-01	116593
Glass Fiber	22	2.50 E-01	102602
Copper	21	2.38 E-01	97938
Gold	8	9.08 E-02	37310
Nickel	11	1.25 E-01	51301
Solder Mask	13	1.48 E-01	60628

Solder Ball

	% of Solder Ball	Weight (g)	PPM
Sn	96.5	5.05 E-01	207493
Cu	0.5	2.62 E-03	1075
Ag	3	1.57 E-02	6451

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.9	1.59 E-02	6517

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.52 E-02	22661

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	2.39 E-03	980
Epoxy resin	5	1.59 E-04	65
Diester	12	3.82 E-04	157
Functionalized Urethane	3	9.54 E-05	39
Functionalized Ester	5	1.59 E-04	65

Package Totals

Weight (g)	PPM
2.43 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA 3050B
Cd	Not Detected	EN1122 Method B: 2001
Hg	Not Detected	US EPA 3052
Cr+6	Not Detected	US EPA 7196A and 3060A
PBB	Not Detected	GC/MS
PBDE	Not Detected	GC/MS

Die Attach

Item	PPM	Method
Pb	5.00	US EPA 3052
Cd	Not Detected	US EPA 3052
Hg	Not Detected	US EPA 3052
Cr+6	Not Detected	US EPA 7196A and 3060A
PBB	Not Detected	GC/MS
PBDE	Not Detected	GC/MS

Laminate

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+06		
PBB		
PBDE		

STS-B-G

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

Materials Declaration

Package	PBGA
Body Size	27 X 27
Ball Count	625
Option	SnPbAg
Ball Size	0.6

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.5	1.00 E+00	406386
Epoxy resin	8	9.48 E-02	38474
Phenol resin	5.5	6.52 E-02	26451
Sb203	0.9	1.07 E-02	4328
Bromine	1.1	1.30 E-02	5290

Laminate

Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	28	1.53 E-01	62232
Glass Fiber	25	1.37 E-01	55564
Copper	18.4	1.01 E-01	40895
Gold	9.8	5.37 E-02	21781
Nickel	7.9	4.33 E-02	17558
Solder Mask(AUS5)	11	6.03 E-02	24448
Brominated Compound	Confidential	Not Determined	

Solder Ball

	% of Solder Ball	Weight (g)	PPM
Sn	62	3.68 E-01	149342
Pb	36	2.14 E-01	86715
Ag	2	1.19 E-02	4817

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.63 E-02	6607

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.00 E-01	40771

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	77	1.58 E-02	6421
Polymer Resin	23	4.73 E-03	1918

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA 3052
Cd	Not Detected	US EPA 3052
Hg	Not Detected	US EPA 3052
Cr+06	Not Detected	US EPA 7196A and 3060A
PBB	Not Detected	GC/MS
PBDE	Not Detected	GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	US EPA 3052
Cd	Not Detected	US EPA 3052
Hg	Not Detected	US EPA 3052
Cr+06	Not Detected	US EPA 7196A and 3060A
PBB	Not Detected	GC/MS
PBDE	Not Detected	GC/MS

Die Attach Paste

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+06		
PBB		
PBDE		

Package Totals

Weight (g)	PPM
2.46 E+00	1000000

STS-B-B

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ANALOG DEVICES

ADI Proprietary

1/27/06